SPW

,	AMENDMENT '	ITER	Docket No. 2019-0214P		
	Application No. 10/655,223-Conf. #6995	Filing Date September 5, 2003	Examiner M. N. Trinh		Art Unit 3729

Applicant(s): Huei-Jen CHEN et al.

변 Ingention: METHOD FOR FABRICATING A SUBSTRATE, INCLUDING A PLURALITY OF CHIP PACKAGE SUBSTRATES

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Transmitted herewith is an amendment in the above-identified application.

		CLAIM	S AS AMENI	DED		_
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present		Rate	
Total Claims	3	- 20 =	0	х		
ndependent Claims	1	- 3 =	0	x		
fultiple Depend	dent Claims (ch	eck if applicabl	e)			
Other fee (pleas	e specify):					
OTAL ADDIT	IONAL FEE FO	OR THIS AME	NDMENT:			0.00
Large Entity					Small Entity	
No addition	al fee is require	d for this ame	ndment.			
	ge Deposit Acc			n the a	mount of \$ _	·
A check in t	ne amount of \$		is enclo	sed.		
Payment by	credit card. Fo	orm PTO-2038	is attached.			
	r is hereby auth d below. A dup					o. <u>02-2448</u>
x Credit a	ny overpaymer	nt.				
x Charge	any additional fil	ing or application	on processing t	fees re	quired under 3	37 CFR 1.16 and 1.17
Joe McKinney Attorney Reg. N		<u></u>			Dated:	May 5, 2006
BIRCH, STEW 8110 Gatehous Suite 100 East	ART, KOLASC	H & BIRCH, LI	LP			





Docket No.: 2019-0214P

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Huei-Jen CHEN et al.

Application No.: 10/655,223

Confirmation No.: 006995

Filed: September 5, 2003

Art Unit: 3729

For: METHOD FOR FABRICATING A

SUBSTRATE, INCLUDING A PLURALITY

OF CHIP PACKAGE SUBSTRATES

Examiner: M. N. Trinh

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 May 5, 2006

Sir:

INTRODUCTORY COMMENTS

In reply to the Office Action dated February 9, 2006, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes:

Amendments to the Specification;

Amendments to the Abstract;

Amendments to the Claims; and

Remarks.